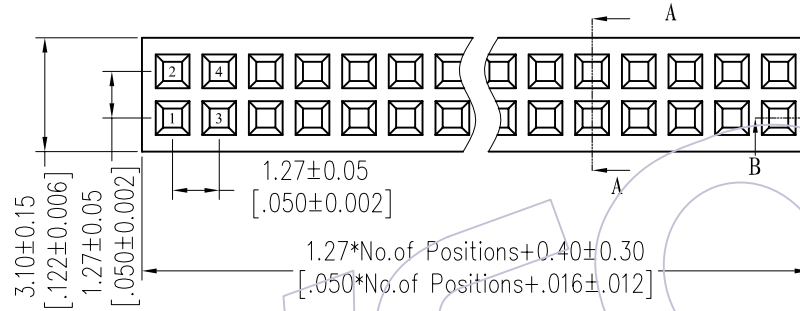
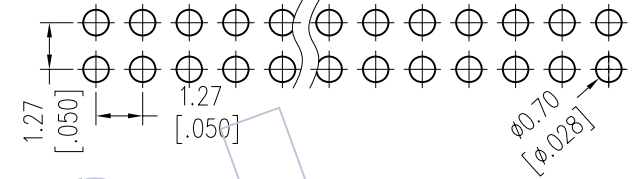


# HSF

NOTES:  
 Current Rating: 1.0AMP  
 Contact Resistance: 20mΩ Max  
 Withstand Voltage: 500V AC/DC  
 Insulation Resistance: 1000MΩ Min  
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze  
 Contact plating: Au over Ni  
 Insulator Material: PA9T+30%GF UL94V-0

Recommended P.C.B Layout (Top Side)  
 (PCB BOARD TOLERANCE ±0.05)



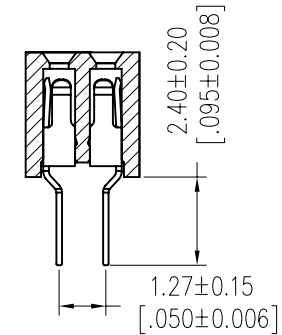
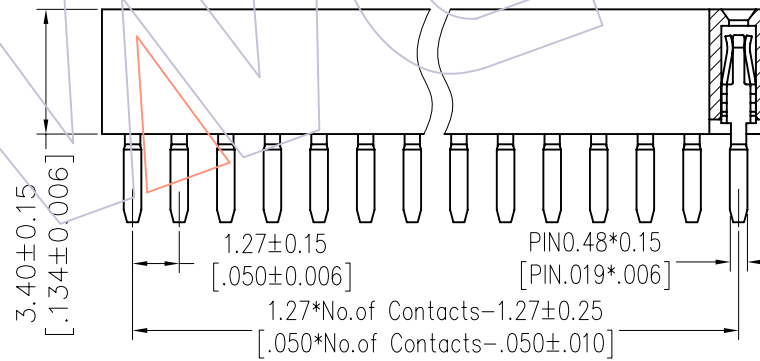
## Ordering Information

2334-2 XX S XX CUN T 1

No. of Pins per Row: 02-50Pin

Contact Plating:  
 G0=Gold Flash  
 G3=10u"Gold  
 G4=15u"Gold  
 G5=30u"Gold

Packing:  
 T=Tube



Section A-A

Section B-B

Item	Pitch	Mating
Standard	1.27	1310/1315/1320
Alternate		

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
				x.x ±0.40	JYHuang	2012/07/06	UNIT	mm	2334-2XXSXXCUNT1
				x.xx ±0.25	CHECK	DATE	SIZE	A4	TITLE:
				x.xxx ±0.15	APPROVE	DATE	SHEET	1/1	FH1.27 DUAL ROW 180° DIP, H=3.40
				Angle ± 3°			PROJ.		Customer NO.
				DIM TOL					